RELIABILITY REPORT

FOR

MAX2410EEI+

PLASTIC ENCAPSULATED DEVICES

October 26, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
Director, Reliability Engineering

Conclusion

The MAX2410EEI+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX2410 performs the RF front-end transmit/receive function in time-division-duplex (TDD) communication systems. It operates over a wide frequency range and is optimized for RF frequencies around 1.9GHz. Applications include most popular cordless and PCS standards. The MAX2410 contains a low-noise amplifier (LNA), a downconverter mixer, a local-oscillator (LO) buffer, an upconverter mixer, and a variable-gain power-amplifier (PA) driver in a low-cost, plastic surface-mount package. The LNA has a 2.4dB (typical) noise figure and a -10dBm input third-order intercept point (IP3). The downconverter mixer has a low 9.8dB noise figure and a 3.3dBm IP3. Image and LO filtering are implemented off-chip for maximum flexibility. The PA driver has 15dB of gain, which can be reduced over a 35dB (typical) range. Power consumption is only 60mW in receive mode or 90mW in transmit mode and drops to less than 0.3µW in shutdown mode. A similar part, the MAX2411A, features the same functionality as the MAX2410 but offers a differential bidirectional (transmit and receive) IF port. This allows the use of a single IF filter for transmit (TX) and receive (RX). For applications requiring a receive function only, consult the data sheet for the MAX2406, a low-cost downconverter with low-noise amplifier.

II. Manufacturing Information

A. Description/Function:	Low-Cost RF Up/Downconverter with LNA and PA Driver
B. Process:	GST2
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	December 19, 1997

III. Packaging Information

A. Package Type:	28-pin QSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-7001-0286
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	93°C/W
K. Single Layer Theta Jc:	27°C/W
L. Multi Layer Theta Ja:	79.3°C/W
M. Multi Layer Theta Jc:	27°C/W

IV. Die Information

A. Dimensions:	55 X 73 mils
B. Passivation:	Si_3N_4 (Silicon nitride)
C. Interconnect:	Au
D. Backside Metallization:	None
E. Minimum Metal Width:	2 microns (as drawn)
F. Minimum Metal Spacing:	2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 150°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 45 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 23.9 \times 10^{-9}$

λ = 23.9 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the GST2 Process results in a FIT Rate of 0.06 @ 25C and 1.10 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The WR27-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-500 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1

Reliability Evaluation Test Results

MAX2410EEI+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 150°C Biased Time = 192 hrs.	DC Parameters & functionality	45	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data